

DP83848J-MAU-EK Purpose and Contents

The purpose of the DP83848J-MAU-EK (EK) is to provide National Semiconductor Corp.'s customers with a vehicle to quickly design and market systems containing the DP83848J chip. Customers are encouraged to copy EK components to expedite their design process. The EK contains:

- DP83848J Media Attachment Unit (MAU)
- · Printed copy of this User's Guide
- DP83848J MAU schematic
- DP83848J MAU licensing agreement

Information and Specifications

This section contains specifications of the DP83848J MAU card, as well as a description of the card's interfaces, connectors, jumpers and the LED.

Usage setup and configuration

- 3.3V power for the DP83848J MAU may be supplied via MII connector. If 3.3V is supplied from the MII connector. R32 needs to be stuffed (See schematics for details)
 - o R33 and R34 should be stuffed for MDIO connection only if 3.3V MII is used
- External 3.3V power is supplied for the DP83848J MAU, if 5V is supplied from the MII connector. R32 should not be stuffed in this case (See schematics for details)
- To set Auto-MDIX ON, do not stuff resistor R30. To set Auto-MDIX OFF, stuff resistor R30 (See schematics for details)
- To configure LED in mode1 for link, do not stuff resistor R31. To configure LED for link and activity, stuff resistor R31 (See schematics for details)
- If the DP83848J MAU card is used for a PHYTERMini device DP83848M/T/H, remove resistor R42 (See schematics for details)

Address settings

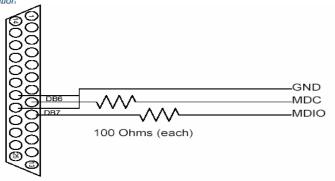
The PMD address for the DP83848J Physical Layer device is set by resistor R29.

- Default board setting for the PHY Address is 01 (Do not stuff resistor R29)
- The board may be set to PHY Address 03 by stuffing resistor R29.

Table of jumpers

| Jumper | Name | Function | |
|--------|----------------|---|--|
| J1 | MII Male | MII interface | |
| | Connector | | |
| J10 | External power | External 3.3V power is supplied for the DP83848J MAU via jumper J10. | |
| | supply | R32 should not be stuffed in this case | |
| J13 | Pulse Jack | Integrated Magnetic RJ-45 connector | |
| J15 | MDIO connector | Connection to the parallel port using Integrity version 3.24 or higher (See | |
| | | Figure below for parallel port to MDIO/MDC connection) | |





Integrity V3.24 Direct connect cable map



DP83848J MAU Specification

Overview

The DP83848J MAU is an NSC demo platform to allow customer evaluation of our device. While the DP83848J has many advanced and enticing features, this specific board is designed to demonstrate *only* a subset of those. The features chosen are the ones that the mainstream customers will use. Thus, we have created an affordable, aesthetic platform to demonstrate the simplicity of designing in a National Semiconductor DP83848J.

Target Environment

Any customer equipment that provides a standard IEEE 802.3, Clause 22 MII DTE interface; e.g. SmartBits/Netcom box.

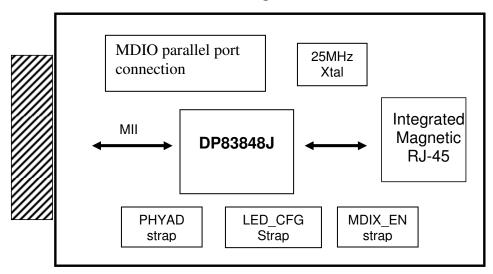
Features/Goals

The DP83848J MAU features:

- Integrated magnetics
- Minimum configuration requirements:
 - o 2 PHY Addresses 01h (default) or 03h
 - 2 LEDs 1 LED for LINK and 1 LED for SPEED
 - Strap Options MDIX_EN, LED_CFG
- Connections for the following interfaces:
 - o MII Interface
 - o Integrated transformer RJ-45
- Standard PCB layout considerations with regards to clock, MII, and TD/RD
- Double sided component placement
- On-board clock Crystal
- On-board power supplied by MII connector, External 3.3V supplied via jumper
- Compact board and Low cost



MAU Block Diagram



PCB Physical Layout requirements / Considerations

- FR4 material
- Trace impedance will be ensured by design:
 - Trace symmetry within differential pair (+/- 0.5")
 - O Differential impedance 100 ohms, +/- 5%
 - Adjacent differential pairs spacing > 2X distance within a differential pair, to minimize cross-talk and EMI
- Trace length matching between differential pairs not required
- Trace space will be 0.007"/0.008" minimum
- Uniform supply & ground plane
- Combination of through-hole and surface mount technology
- Target size 2.05" (height), 1.5" (length)
- 4 lavers
- Silk screen on two sides

MAU Interface requirements

- System interface will be via the MII connector, and MII header
- RJ-45 for network connection

Software

No device specific software is required for this board
 National does provide the integrity utility; a diagnostic and configuration package at www.national.com/appinfo/networks/ethernet_utility.html

Additional information

Updated versions of the included material, related material can be found by going to ethernet.national.com or directly to design resources at http://www.national.com/appinfo/networks/webench/dp83848.html



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